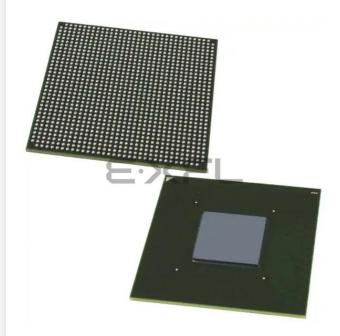
Intel - 5AGXMB5G4F35I5N Datasheet





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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Details	
Product Status	Obsolete
Number of LABs/CLBs	19811
Number of Logic Elements/Cells	420000
Total RAM Bits	23625728
Number of I/O	544
Number of Gates	·
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxmb5g4f35i5n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Symbol	Description	Condition (V)	Ca	libration Accura	Unit	
Symbol	Description		–I3, –C4	–I5, –C5	-C6	Onic
60- Ω and 120- Ω R_T	Internal parallel termination with calibration (60- Ω and 120- Ω setting)	$V_{CCIO} = 1.2$	-10 to +40	-10 to +40	-10 to +40	%
25- Ω R _{S_left_shift}	Internal left shift series termination with calibration (25- $\Omega R_{S_left_shift}$ setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	±15	±15	±15	%

OCT Without Calibration Resistance Tolerance Specifications

Table 1-9: OCT Without Calibration Resistance Tolerance Specifications for Arria V Devices

This table lists the Arria V OCT without calibration resistance to PVT changes.

Symbol	Description	Condition (V)	Re	sistanceToleran	ice	Unit
Symbol	Description		-I3, -C4	–I5, –C5	-C6	Ont
25-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 3.0, 2.5	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 1.8, 1.5	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25- Ω setting)	$V_{CCIO} = 1.2$	±35	±50	±50	%
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCIO} = 3.0, 2.5	±30	±40	±40	%
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCIO} = 1.8, 1.5	±30	±40	±40	%
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	$V_{CCIO} = 1.2$	±35	±50	±50	%
100-Ω R _D	Internal differential termination (100- Ω setting)	$V_{CCIO} = 2.5$	±25	±40	±40	%



Sumbol/Decovintion	Condition	Transc	eiver Speed G	irade 4	Transc	eiver Speed G	Unit	
Symbol/Description	Condition	Min	Тур	Max	Min	Тур	Max	Onit
Minimum differential eye opening at the receiver serial input pins ⁽³⁰⁾	_	100	_	_	100	_	_	mV
V _{ICM} (AC coupled)	_	_	0.7/0.75/ 0.8 ⁽³¹⁾	_	_	0.7/0.75/ 0.8 ⁽³¹⁾		mV
V _{ICM} (DC coupled)	$\leq 3.2 \text{Gbps}^{(32)}$	670	700	730	670	700	730	mV
	85- Ω setting		85	—		85	_	Ω
Differential on-chip	100- Ω setting		100	_		100		Ω
termination resistors	120-Ω setting		120	—		120		Ω
	150-Ω setting		150	_		150		Ω
t _{LTR} ⁽³³⁾		_	_	10	_	_	10	μs
$t_{LTD}^{(34)}$	_	4	_	_	4	_	_	μs
t _{LTD_manual} ⁽³⁵⁾	_	4	_	—	4	_	_	μs
t _{LTR_LTD_manual} ⁽³⁶⁾		15	_		15			μs
Programmable ppm detector ⁽³⁷⁾	_		±62.5, 100, 125, 200, 250, 300, 500, and 1000					

⁽³⁰⁾ The differential eye opening specification at the receiver input pins assumes that you have disabled the **Receiver Equalization** feature. If you enable the **Receiver Equalization** feature, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

(31) The AC coupled $V_{ICM} = 700 \text{ mV}$ for Arria V GX and SX in PCIe mode only. The AC coupled $V_{ICM} = 750 \text{ mV}$ for Arria V GT and ST in PCIe mode only.

⁽³²⁾ For standard protocol compliance, use AC coupling.

 $^{(33)}$ t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.

 $^{(34)}$ t_{LTD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.

 $^{(35)}$ t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.

 $t_{\text{LTR_LTD_manual}}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.



Table 1-34: Transceiver Compliance Specification for All Supported Protocol for Arria V GX, GT, SX, and ST Devices

Protocol	Sub-protocol	Data Rate (Mbps)
	PCIe Gen1	2,500
PCIe	PCIe Gen2	5,000
	PCIe Cable	2,500
XAUI	XAUI 2135	3,125
	SRIO 1250 SR	1,250
	SRIO 1250 LR	1,250
	SRIO 2500 SR	2,500
	SRIO 2500 LR	2,500
	SRIO 3125 SR	3,125
Serial RapidIO [®] (SRIO)	SRIO 3125 LR	3,125
Serial Rapidio (SRIO)	SRIO 5000 SR	5,000
	SRIO 5000 MR	5,000
	SRIO 5000 LR	5,000
	SRIO_6250_SR	6,250
	SRIO_6250_MR	6,250
	SRIO_6250_LR	6,250



Symbol	Parameter	Condition	Min	Тур	Max	Unit
		-3 speed grade	_	_	670 ⁽⁶³⁾	MHz
f	Output frequency for external clock	-4 speed grade	_	_	670 ⁽⁶³⁾	MHz
f _{out_ext}	output	–5 speed grade	_	_	622 ⁽⁶³⁾	MHz
		-6 speed grade			500 ⁽⁶³⁾	MHz
t _{OUTDUTY}	Duty cycle for external clock output (when set to 50%)		45	50	55	%
t _{FCOMP}	External feedback clock compensation time	_	_	_	10	ns
t _{DYCONFIGCLK}	Dynamic configuration clock for mgmt_ clk and scanclk	_	_	_	100	MHz
t _{LOCK}	Time required to lock from end-of- device configuration or deassertion of areset	_	_		1	ms
t _{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_			1	ms
		Low	_	0.3	_	MHz
f _{CLBW}	PLL closed-loop bandwidth	Medium	_	1.5	_	MHz
		High ⁽⁶⁴⁾	_	4	_	MHz
t _{PLL_PSERR}	Accuracy of PLL phase shift	—	_	_	±50	ps
t _{ARESET}	Minimum pulse width on the areset signal	_	10	_	_	ns
+ (65)(66)	Input dock and to and ittar	$F_{REF} \ge 100 \text{ MHz}$	_	_	0.15	UI (p-p)
t _{INCCJ} ⁽⁶⁵⁾⁽⁶⁶⁾	Input clock cycle-to-cycle jitter	$F_{REF} < 100 \text{ MHz}$	_	_	±750	ps (p-p)

⁽⁶⁴⁾ High bandwidth PLL settings are not supported in external feedback mode.



⁽⁶⁵⁾ A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source with jitter < 120 ps.

⁽⁶⁶⁾ F_{REF} is f_{IN}/N , specification applies when N = 1.

1-46	PLL Specifications
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Symbol	Parameter	Condition	Min	Тур	Max	Unit
+ (67)	Period jitter for dedicated clock output	$F_{OUT} \ge 100 \text{ MHz}$	—	_	175	ps (p-p)
t _{outpj_dc} ⁽⁶⁷⁾	in integer PLL	$F_{OUT} < 100 \text{ MHz}$	—	_	17.5	mUI (p-p)
t(67)	Period jitter for dedicated clock output	$F_{OUT} \ge 100 \text{ MHz}$			250 ⁽⁶⁸⁾ , 175 ⁽⁶⁹⁾	ps (p-p)
t _{FOUTPJ_DC} ⁽⁶⁷⁾	in fractional PLL	$F_{OUT} < 100 \text{ MHz}$			25 ⁽⁶⁸⁾ , 17.5 ⁽⁶⁹⁾	mUI (p-p)
t	Cycle-to-cycle jitter for dedicated clock	$F_{OUT} \ge 100 \text{ MHz}$	_		175	ps (p-p)
t _{OUTCCJ_DC} ⁽⁶⁷⁾	output in integer PLL	$F_{OUT} < 100 \text{ MHz}$	_		17.5	mUI (p-p)
+ (67)	Cycle-to-cycle jitter for dedicated clock	$F_{OUT} \ge 100 \text{ MHz}$	_		250 ⁽⁶⁸⁾ , 175 ⁽⁶⁹⁾	ps (p-p)
t _{FOUTCCJ_DC} ⁽⁶⁷⁾	output in fractional PLL	$F_{OUT} < 100 \text{ MHz}$	—		25 ⁽⁶⁸⁾ , 17.5 ⁽⁶⁹⁾	mUI (p-p)
t _{OUTPJ_IO} ⁽⁶⁷⁾⁽⁷⁰⁾	Period jitter for clock output on a	$F_{OUT} \ge 100 \text{ MHz}$	_		600	ps (p-p)
OUTPJ_IO	regular I/O in integer PLL	$F_{OUT} < 100 MHz$	_	_	60	mUI (p-p)
t _{FOUTPJ_IO} ⁽⁶⁷⁾⁽⁶⁸⁾⁽⁷⁰⁾	Period jitter for clock output on a	$F_{OUT} \ge 100 \text{ MHz}$	—		600	ps (p-p)
FOUTPJ_IO	regular I/O in fractional PLL	$F_{OUT} < 100 \text{ MHz}$			60	mUI (p-p)
t (67)(70)	Cycle-to-cycle jitter for clock output on	$F_{OUT} \ge 100 \text{ MHz}$			600	ps (p-p)
t _{OUTCCJ_IO} ⁽⁶⁷⁾⁽⁷⁰⁾	a regular I/O in integer PLL	$F_{OUT} < 100 \text{ MHz}$	—	_	60	mUI (p-p)
t (67)(68)(70)	Cycle-to-cycle jitter for clock output on	$F_{OUT} \ge 100 \text{ MHz}$	_		600	ps (p-p)
t _{FOUTCCJ_IO} ⁽⁶⁷⁾⁽⁶⁸⁾⁽⁷⁰⁾	a regular I/O in fractional PLL	$F_{OUT} < 100 \text{ MHz}$			60	mUI (p-p)



⁽⁶⁷⁾ Peak-to-peak jitter with a probability level of 10⁻¹² (14 sigma, 99.99999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Memory Output Clock Jitter Specification for Arria V Devices table.

⁽⁶⁸⁾ This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05–0.95 must be \geq 1000 MHz.

⁽⁶⁹⁾ This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.20–0.80 must be \geq 1200 MHz.

⁽⁷⁰⁾ External memory interface clock output jitter specifications use a different measurement method, which are available in Memory Output Clock Jitter Specification for Arria V Devices table.

Symbol	Condition		-I3, -C4			–I5, –C5			-C6		Unit
Symbol	Condition	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
	SERDES factor J ≥ 8 ⁽⁷⁶⁾⁽⁷⁸⁾ , LVDS TX with RX DPA	(77)		1600	(77)		1500	(77)	_	1250	Mbps
	SERDES factor J = 1 to 2, Uses DDR Registers	(77)		(79)	(77)		(79)	(77)	_	(79)	Mbps
Emulated Differential I/ O Standards with Three External Output Resistor Network - f _{HSDR} (data rate) ⁽⁸⁰⁾	SERDES factor $J = 4$ to $10^{(81)}$	(77)		945	(77)		945	(77)		945	Mbps
Emulated Differential I/ O Standards with One External Output Resistor Network - f _{HSDR} (data rate) ⁽⁸⁰⁾	SERDES factor $J = 4$ to $10^{(81)}$	(77)		200	(77)		200	(77)		200	Mbps
t _{x Jitter} -True Differential I/O Standards	Total Jitter for Data Rate 600 Mbps – 1.25 Gbps			160			160		_	160	ps
	Total Jitter for Data Rate < 600 Mbps			0.1	_	_	0.1	—	_	0.1	UI



 $^{^{(78)}}$ The V_{CC} and V_{CCP} must be on a separate power layer and a maximum load of 5 pF for chip-to-chip interface.

⁽⁷⁹⁾ The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (f_{OUT}), provided you can close the design timing and the signal integrity simulation is clean.

⁽⁸⁰⁾ You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine the leftover timing margin.

⁽⁸¹⁾ When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

DPA Lock Time Specifications

Figure 1-4: Dynamic Phase Alignment (DPA) Lock Time Specifications with DPA PLL Calibration Enabled

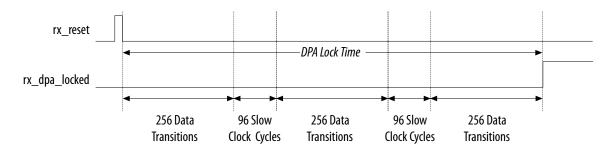


Table 1-41: DPA Lock Time Specifications for Arria V Devices

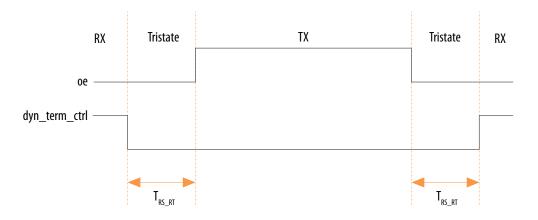
The specifications are applicable to both commercial and industrial grades. The DPA lock time is for one channel. One data transition is defined as a 0-to-1 or 1-to-0 transition.

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions ⁽⁸⁴⁾	Maximum Data Transition
SPI-4	0000000001111111111	2	128	640
Parallel Rapid I/O	00001111	2	128	640
r araner Rapid 1/0	10010000	4	64	640
Miscellaneous	10101010	8	32	640
wiscenaneous	01010101	8	32	640

⁽⁸⁴⁾ This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.



Figure 1-7: Timing Diagram for oe and dyn_term_ctrl Signals



Duty Cycle Distortion (DCD) Specifications

Table 1-47: Worst-Case DCD on Arria V I/O Pins

The output DCD cycle only applies to the I/O buffer. It does not cover the system DCD.

Symbol	–I3,	-C4	-C5	, –15	-(26	Unit
Symbol	Min	Мах	Min	Мах	Min	Мах	Ont
Output Duty Cycle	45	55	45	55	45	55	%

HPS Specifications

This section provides HPS specifications and timing for Arria V devices.

For HPS reset, the minimum reset pulse widths for the HPS cold and warm reset signals (HPS_nRST and HPS_nPOR) are six clock cycles of HPS_CLK1.



Figure 1-9: SPI Master Timing Diagram

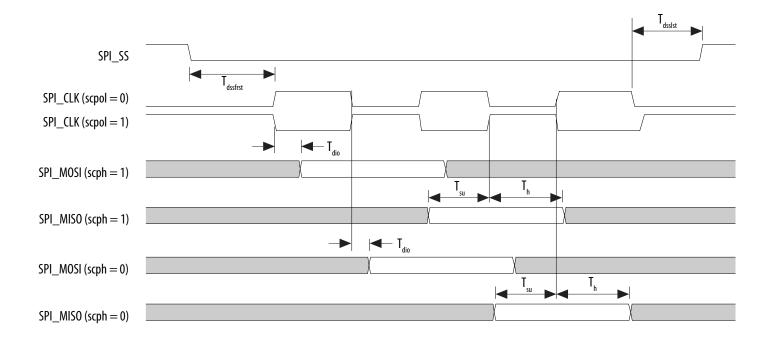


Table 1-53: SPI Slave Timing Requirements for Arria V Devices

The setup and hold times can be used for Texas Instruments SSP mode and National Semiconductor Microwire mode.

Symbol	Description	Min	Max	Unit
T _{clk}	CLK clock period	20		ns
T _s	MOSI Setup time	5		ns
T _h	MOSI Hold time	5		ns
T _{suss}	Setup time SPI_SS valid before first clock edge	8		ns
T _{hss}	Hold time SPI_SS valid after last clock edge	8		ns
T _d	MISO output delay		6	ns



Related Information

- PS Configuration Timing on page 1-81
- AS Configuration Timing

Provides the AS configuration timing waveform.

DCLK Frequency Specification in the AS Configuration Scheme

Table 1-69: DCLK Frequency Specification in the AS Configuration Scheme

This table lists the internal clock frequency specification for the AS configuration scheme. The DCLK frequency specification applies when you use the internal oscillator as the configuration clock source. The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Parameter	Minimum	Typical	Maximum	Unit
	5.3	7.9	12.5	MHz
DCLK frequency in AS configuration scheme	10.6	15.7	25.0	MHz
Bellk frequency in AS configuration scheme	21.3	31.4	50.0	MHz
	42.6	62.9	100.0	MHz

PS Configuration Timing

Table 1-70: PS Timing Parameters for Arria V Devices

Symbol	Parameter	Minimum	Maximum	Unit
t _{CF2CD}	nCONFIG low to CONF_DONE low	_	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low		600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μs
t _{STATUS}	nSTATUS low pulse width	268	1506 ⁽¹⁰³⁾	μs
t _{CF2ST1}	nCONFIG high to nSTATUS high	_	1506(104)	μs

 $^{^{(103)}\,}$ You can obtain this value if you do not delay configuration by extending the <code>nCONFIG</code> or <code>nSTATUS</code> low pulse width.



⁽¹⁰⁴⁾ You can obtain this value if you do not delay configuration by externally holding nSTATUS low.

The Quartus Prime Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

Related Information

Arria V I/O Timing Spreadsheet

Provides the Arria V Excel-based I/O timing spreadsheet.

Programmable IOE Delay

Parameter ⁽¹¹²	meter ⁽¹¹² Available Minimum			Fast Model		Slow Model				Unit	
)	Settings Offset ⁽¹¹		Industrial	Commercial	-C4	-C5	-C6	-13	-15	Onic	
D1	32	0	0.508	0.517	0.870	1.063	1.063	0.872	1.057	ns	
D3	8	0	1.763	1.795	2.999	3.496	3.571	3.031	3.643	ns	
D4	32	0	0.508	0.518	0.869	1.063	1.063	1.063	1.057	ns	
D5	32	0	0.508	0.517	0.870	1.063	1.063	0.872	1.057	ns	

Table 1-76: I/O element (IOE) Programmable Delay for Arria V Devices

Programmable Output Buffer Delay

Table 1-77: Programmable Output Buffer Delay for Arria V Devices

This table lists the delay chain settings that control the rising and falling edge delays of the output buffer.

You can set the programmable output buffer delay in the Quartus Prime software by setting the **Output Buffer Delay Control** assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the **Output Buffer Delay** assignment.



⁽¹¹²⁾ You can set this value in the Quartus Prime software by selecting **D1**, **D3**, **D4**, and **D5** in the **Assignment Name** column of **Assignment Editor**.

⁽¹¹³⁾ Minimum offset does not include the intrinsic delay.

Date	Version	Changes
June 2012	2.0	 Updated for the Quartus II software v12.0 release: Restructured document. Updated "Supply Current and Power Consumption" section. Updated Table 20, Table 21, Table 24, Table 25, Table 26, Table 35, Table 39, Table 43, and Table 52. Added Table 22, Table 23, and Table 33. Added Figure 1–1 and Figure 1–2. Added "Initialization" and "Configuration Files" sections.
February 2012	1.3	 Updated Table 2–1. Updated Transceiver-FPGA Fabric Interface rows in Table 2–20. Updated V_{CCP} description.
December 2011	1.2	Updated Table 2–1 and Table 2–3.
November 2011	1.1	 Updated Table 2–1, Table 2–19, Table 2–26, and Table 2–36. Added Table 2–5. Added Figure 2–4.
August 2011	1.0	Initial release.



2-4 Recommended Operating Conditions

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle.

For example, a signal that overshoots to 3.95 V can be at 3.95 V for only $\sim 21\%$ over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~ 2 years.

Table 2-4: Maximum Allowed Overshoot During Transitions for Arria V GZ Devices
--

Symbol	Description	Condition (V)	Overshoot Duration as $\% @ T_J = 100^{\circ}C$	Unit
		3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
Vi (AC)	AC input voltage	4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Recommended Operating Conditions

Table 2-5: Recommended Operating Conditions for Arria V GZ Devices

Power supply ramps must all be strictly monotonic, without plateaus.

Symbol	Description	Condition	Minimum ⁽¹¹⁴⁾	Typical	Maximum ⁽¹¹⁴⁾	Unit
V _{CC}	Core voltage and periphery circuitry power supply (115)	_	0.82	0.85	0.88	V

⁽¹¹⁴⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.





⁽¹¹⁵⁾ The V_{CC} core supply must be set to 0.9 V if the Partial Reconfiguration (PR) feature is used.

Transceiver Power Supply Requirements

Table 2-7: Transceiver Power Supply Voltage Requirements for Arria V GZ Devices

Conditions	VCCR_GXB and VCCT_GXB ⁽¹²²⁾	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true:	1.05			
 Data rate > 10.3 Gbps. DFE is used. 				
If ANY of the following conditions are true ⁽¹²³⁾ :	1.0	3.0		
 ATX PLL is used. Data rate > 6.5Gbps. DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used. 			1.5	V
If ALL of the following conditions are true:	0.85	2.5		
 ATX PLL is not used. Data rate ≤ 6.5Gbps. DFE, AEQ, and EyeQ are not used. 				

DC Characteristics

Supply Current

Standby current is the current drawn from the respective power rails used for power budgeting.

Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.



Send Feedback

⁽¹²²⁾ If the VCCR_GXB and VCCT_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR_GXB and VCCT_GXB are set to 0.85 V, they can be shared with the VCC core supply.

⁽¹²³⁾ Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.

Related Information

- PowerPlay Early Power Estimator User Guide For more information about the EPE tool.
- **PowerPlay Power Analysis** ٠ For more information about PowerPlay power analysis.

Power Consumption

Altera offers two ways to estimate power consumption for a design-the Excel-based Early Power Estimator and the Quartus II PowerPlay Power Analyzer feature.

Note: You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

Related Information

- PowerPlay Early Power Estimator User Guide For more information about the EPE tool.
- PowerPlay Power Analysis For more information about PowerPlay power analysis.

I/O Pin Leakage Current

Table 2-8: I/O Pin Leakage Current for Arria V GZ Devices

If $V_O = V_{CCIO}$ to $V_{CCIOMax}$, 100 µA of leakage current per I/O is expected.

Symbol	Description	Conditions	Min	Тур	Max	Unit
II	Input pin	$V_{I} = 0 V$ to $V_{CCIOMAX}$	-30		30	μΑ
I _{OZ}	Tri-stated I/O pin	$V_{O} = 0 V$ to $V_{CCIOMAX}$	-30	—	30	μΑ



I/O Standard	V _{IL(D}	_{C)} (V)	V _{IH(D0}	_{_)} (V)	V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	L (m A)	I (m A)
I/O Standard	Min	Max	Min	Max	Max	Min	Max	Min	l _{ol} (mA)	l _{oh} (mA)
SSTL-18 Class II	-0.3	V _{REF} – 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} – 0.25	V _{REF} + 0.25	0.28	V _{CCIO} – 0.28	13.4	-13.4
SSTL-15 Class I		V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} – 0.175	V _{REF} + 0.175	$0.2 \times V_{ m CCIO}$	$0.8 \times V_{ m CCIO}$	8	-8
SSTL-15 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	—	V _{REF} – 0.175	V _{REF} + 0.175	$0.2 \times V_{\rm CCIO}$	$0.8 \times V_{ m CCIO}$	16	-16
SSTL-135 Class I, II		V _{REF} – 0.09	V _{REF} + 0.09	_	V _{REF} – 0.16	V _{REF} + 0.16	0.2 * V _{CCIO}	0.8 * V _{CCIO}	—	—
SSTL-125 Class I, II	_	V _{REF} – 0.85	V _{REF} + 0.85	—	V _{REF} – 0.15	V _{REF} + 0.15	0.2 * V _{CCIO}	0.8 * V _{CCIO}	—	—
SSTL-12 Class I, II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} – 0.15	V _{REF} + 0.15	0.2 * V _{CCIO}	0.8 * V _{CCIO}	—	_
HSTL-18 Class I		V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	8	-8
HSTL-18 Class II		V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	16	-16
HSTL-15 Class I		V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} – 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	8	-8
HSTL-15 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} – 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	16	-16
HSTL-12 Class I	-0.15	V _{REF} – 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} – 0.15	V _{REF} + 0.15	$0.25 \times V_{\rm CCIO}$	$0.75 \times V_{ m CCIO}$	8	-8
HSTL-12 Class II	-0.15	V _{REF} – 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} – 0.15	V _{REF} + 0.15	$0.25 \times V_{\rm CCIO}$	$0.75 \times V_{ m CCIO}$	16	-16
HSUL-12	—	V _{REF} – 0.13	V _{REF} + 0.13	—	V _{REF} – 0.22	V _{REF} + 0.22	$0.1 \times V_{\rm CCIO}$	$0.9 \times V_{ m CCIO}$	—	—

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Symbol	Parameter	Min	Тур	Мах	Unit
t _{INCCJ} ⁽¹⁷¹⁾ , ⁽¹⁷²⁾	Input clock cycle-to-cycle jitter (f_{REF} $\geq 100~MHz)$	—	_	0.15	UI (p-p)
'INCCJ , , , , , ,	Input clock cycle-to-cycle jitter ($f_{REF} < 100 \text{ MHz}$)	-750		+750	ps (p-p)
(173)	Period Jitter for dedicated clock output in integer PLL ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	175	ps (p-p)
t _{OUTPJ_DC} ⁽¹⁷³⁾	Period Jitter for dedicated clock output in integer PLL (f _{OUT} < 100 Mhz)	_		17.5	mUI (p-p)
(173)	Period Jitter for dedicated clock output in fractional PLL ($f_{OUT} \ge 100 \text{ MHz}$)	_		$250^{(176)}, \\ 175^{(174)}$	ps (p-p)
t _{FOUTPJ_DC} ⁽¹⁷³⁾	Period Jitter for dedicated clock output in fractional PLL (f _{OUT} < 100 MHz)	—		$25^{(176)}$, 17.5 ⁽¹⁷⁴⁾	mUI (p-p)
tournoon = c (173)	Cycle-to-cycle Jitter for a dedicated clock output in integer PLL ($f_{OUT} \ge 100 \text{ MHz}$)	—		175	ps (p-p)
t _{OUTCCJ_DC} ⁽¹⁷³⁾	Cycle-to-cycle Jitter for a dedicated clock output in integer PLL ($f_{OUT} < 100 \text{ MHz}$)	_		17.5	mUI (p-p)
(173)	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ($f_{OUT} \ge 100 \text{ MHz}$)	—		250 ⁽¹⁷⁶⁾ , 175 ⁽¹⁷⁴⁾	ps (p-p)
t _{FOUTCCJ_DC} ⁽¹⁷³⁾	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ($f_{OUT} < 100 \text{ MHz}$)			$25^{(176)}$, 17.5 ⁽¹⁷⁴⁾	mUI (p-p)

⁽¹⁷¹⁾ A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source with jitter < 120 ps. ⁽¹⁷²⁾ The f_{REF} is fIN/N specification applies when N = 1.

⁽¹⁷⁴⁾ This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.20–0.80 must be \geq 1200 MHz.



⁽¹⁷³⁾ Peak-to-peak jitter with a probability level of 10⁻¹² (14 sigma, 99.999999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in the "Worst-Case DCD on Arria V GZ I/O Pins" table.

Table 2-55: DCLK-to-DATA[] Ratio for Arria V GZ Devices

Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA[] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Arria V GZ devices use the additional clock cycles to decrypt and decompress the configuration data.

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×8	Disabled	Enabled	1
FFF X0	Enabled	Disabled	2
	Enabled	Enabled	2
	Disabled	Disabled	1
FPP ×16	Disabled	Enabled	2
111 ×10	Enabled	Disabled	4
	Enabled	Enabled	4
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
111 / 52	Enabled	Disabled	8
	Enabled	Enabled	8





Symbol	Parameter	Minimum	Maximum	Unit
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	$4 \times maximum$	—	—
		DCLK period		
t _{CD2UM} C	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period) (209)	_	_

Related Information

- DCLK-to-DATA[] Ratio (r) for FPP Configuration on page 2-57 ٠
- Configuration, Design Security, and Remote System Upgrades in Arria V Devices

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⁽²⁰⁸⁾ The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

⁽²⁰⁹⁾ To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section of the Configuration, Design Security, and Remote System Upgrades in Arria V Devices chapter.

Glossary

Table 2-68: Glossary

